1st DRD3 week on Solid State Detectors R&D

Wednesday 19 June 2024

WG7/WP4 - Interconnect technologies: WG7 talks - 500/1-001 - Main Auditorium (13:00 - 15:40)

-Conveners: Dominik Dannheim; Giovanni Calderini; Fabian Huegging

time	[id] title	presenter
13:00	[55] Development of an in-house Ni/Au plating process for pixel-detector hybridisation and module integration	BANGARU, Haripriya
13:15	[40] Development of adhesive-based pixel-detector hybridisation concepts	SVIHRA, Peter
13:30	[10] Interconnections and multi-chip flex developments	SHARMA, Abhishek
13:45	[74] 100μPET MAPS stack: 3D pixels enabling ultra-high resolution PET imaging	VICENTE BARRETO PINTO, Mateus
14:00	[3] Highly Integrated All-Silicon Detector Modules - Belle II PXD and beyond	ANDRICEK, Laci
14:15	[39] Ultra-thin hybrid pixel detectors using Wafer-to-Wafer bonding	HUEGGING, Fabian
14:30	[84] Discussion on Interconnect	
15:00	Coffee Break	